

# CS8311

## Micropower 10 V, 100 mA Low Dropout Linear Regulator with **RESET** and **ENABLE**

The CS8311 is a precision 10 V micropower voltage regulator with very low quiescent current (100  $\mu$ A typ at 100  $\mu$ A load). The 10 V output is accurate within  $\pm 4.0\%$  and supplies 100 mA of load current with a typical dropout voltage of only 400 mV. Microprocessor control logic includes an **ENABLE** input and an active **RESET**.

The active **RESET** circuit includes hysteresis, and operates correctly at an output voltage as low as 1.0 V. The **RESET** function is activated during the power up sequence or during normal operation if the output voltage drops outside the regulation limits by more than 1.0 V typ. The logic level compatible **ENABLE** input allows the user to put the regulator into a shutdown mode where it draws only 20  $\mu$ A typical of quiescent current.

The regulator is protected against reverse battery, short circuit, over voltage, and thermal overload conditions. The device can withstand load dump transients making it suitable for use in automotive environments.

### Features

- 10 V  $\pm 4.0\%$  Output
- Low 100  $\mu$ A Quiescent Current
- Active **RESET**
- **ENABLE** Input for ON/OFF and Active/Sleep Mode Control
- 100 mA Output Current Capability
- Fault Protection
  - +60 V Peak Transient Voltage
  - -15 V Reverse Voltage Short Circuit Thermal Overload
- Low Reverse Current (Output to Input)



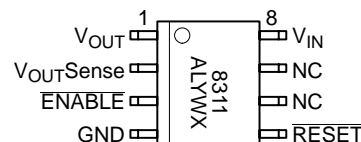
ON Semiconductor™

<http://onsemi.com>



SO-8  
D SUFFIX  
CASE 751

### PIN CONNECTIONS AND MARKING DIAGRAM



A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week

### ORDERING INFORMATION

Device	Package	Shipping
CS8311YD8	SO-8	95 Units/Rail
CS8311YDR8	SO-8	2500 Tape & Reel

# CS8311

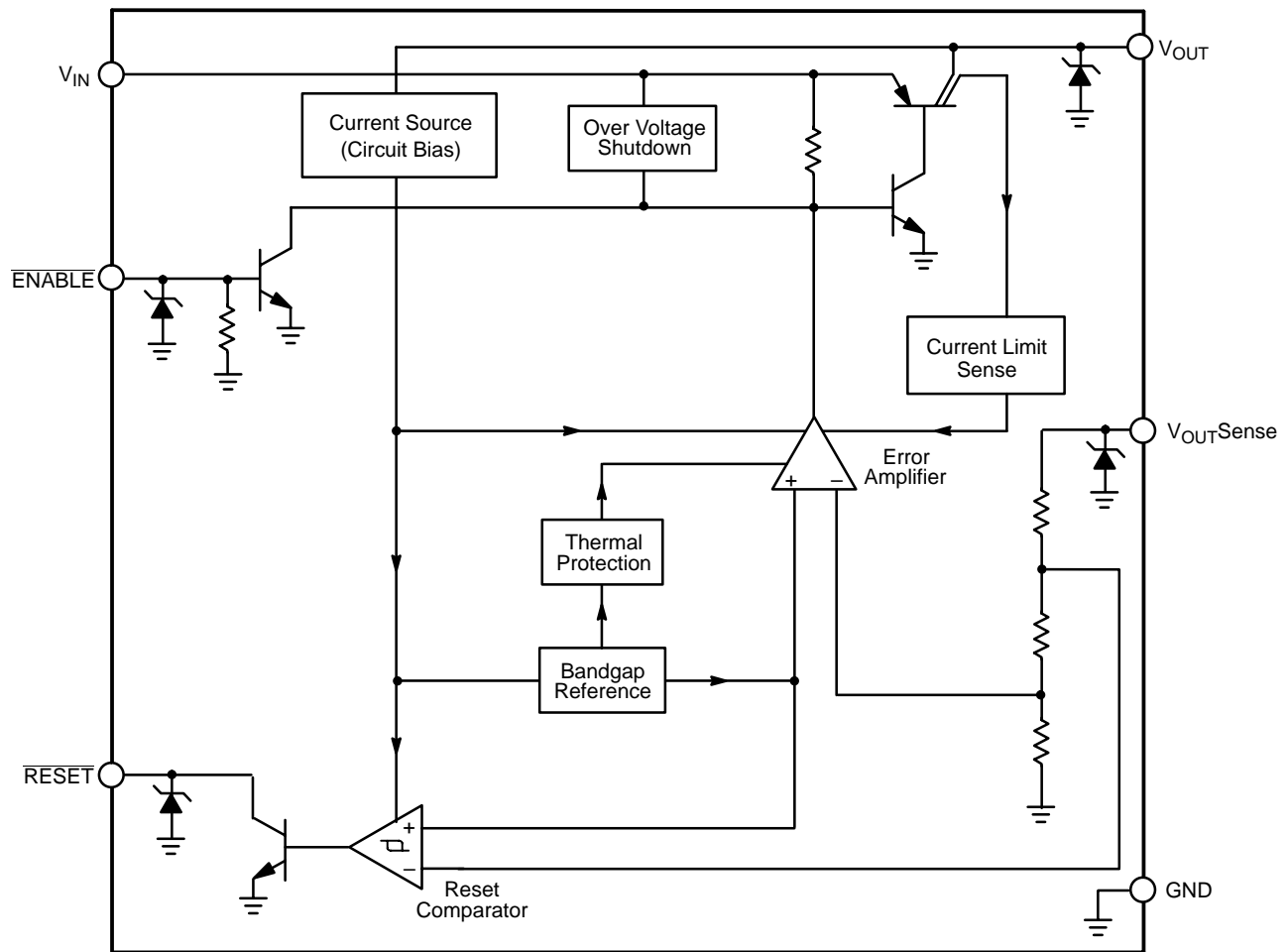


Figure 1. Block Diagram

## ABSOLUTE MAXIMUM RATINGS\*

Rating	Value	Unit
$V_{IN}$	38	V
Peak Transient Voltage (46 V Load Dump @ $V_{IN} = 14$ V)	60	V
ENABLE, RESET	-0.3 to +10.4	V
ESD Susceptibility (Human Body Model)	2.0	kV
Junction Temperature Range	-40 to +150	°C
Storage Temperature Range	-55 to +150	°C
Lead Temperature Soldering:	Reflow (SMD styles only) (Note 1.)	230 peak

1. 60 second maximum above 183°C.

\*The maximum package power dissipation must be observed.

# CS8311

**ELECTRICAL CHARACTERISTICS** (11 V ≤ V<sub>IN</sub> ≤ 26 V; I<sub>OUT</sub> = 1.0 mA; −40 ≤ T<sub>A</sub> ≤ 125, −40°C ≤ T<sub>J</sub> ≤ 150°C; unless otherwise specified.)

Characteristic	Test Conditions	Min	Typ	Max	Unit
<b>Output Stage</b>					
Output Voltage, V <sub>OUT</sub>	11 V < V <sub>IN</sub> < 26 V, 100 μA ≤ I <sub>OUT</sub> ≤ 100 mA	9.60	10.00	10.40	V
Dropout Voltage (V <sub>IN</sub> − V <sub>OUT</sub> )	I <sub>OUT</sub> = 100 mA I <sub>OUT</sub> = 100 μA	– –	400 100	600 150	mV mV
Load Regulation	V <sub>IN</sub> = 14 V, 100 μA ≤ I <sub>OUT</sub> ≤ 100 mA	–	5.0	100	mV
Line Regulation	11 V < V < 26 V, I <sub>OUT</sub> = 1.0 mA	–	5.0	100	mV
Quiescent Current, (I <sub>Q</sub> ) Active Mode	I <sub>OUT</sub> = 100 μA I <sub>OUT</sub> = 50 mA I <sub>OUT</sub> = 100 mA	– – –	100 4.0 12	250 6.0 20	μA mA mA
Quiescent Current, (I <sub>Q</sub> ) Sleep Mode	V <sub>OUT</sub> = OFF, V <sub>IN</sub> = 12 V, V <sub>ENABLE</sub> = 2.0 V	–	20	50	μA
Ripple Rejection	14 ≤ V <sub>IN</sub> ≤ 26 V, I <sub>OUT</sub> = 100 mA, f = 120 Hz	60	75	–	dB
Current Limit	–	105	200	–	mA
Short Circuit Output Current	V <sub>OUT</sub> = 0 V	25	125	–	mA
Overvoltage Shutdown	V <sub>OUT</sub> ≤ 1.0 V	30	34	38	V
Reverse Current	V <sub>OUT</sub> = 5.0 V, V <sub>IN</sub> = 0 V	–	100	250	μA

## ENABLE Input (ENABLE)

Threshold High	(V <sub>OUT</sub> OFF)	–	1.4	2.0	V
Threshold Low	(V <sub>OUT</sub> ON)	0.6	1.4	–	V
Input Current	V <sub>ENABLE</sub> = 2.4 V	–	30	100	μA

## Reset Function (RESET)

RESET Threshold High (V <sub>RH</sub> )	V <sub>OUT</sub> Increasing	8.50	9.00	V <sub>OUT</sub> − 0.50	V
RESET Threshold Low (V <sub>RL</sub> )	V <sub>OUT</sub> Decreasing	8.30	8.90	V <sub>OUT</sub> − 0.45	V
RESET Hysteresis	(High − Low)	50	100	200	mV
Reset Output Leakage RESET = High	V <sub>OUT</sub> ≥ V <sub>RH</sub>	–	–	25	μA
Output Voltage Low (V <sub>RLO</sub> )	R <sub>RESET</sub> = 10 k, 1.0 V ≤ V <sub>OUT</sub> ≤ V <sub>RL</sub>	–	0.1	0.4	V
Output Voltage Low (V <sub>RPEAK</sub> )	R <sub>RESET</sub> = 10 k, V <sub>OUT</sub> : Power up, Power down	–	0.6	1.0	V

## PACKAGE LEAD DESCRIPTION

PACKAGE LEAD #	LEAD SYMBOL	FUNCTION
SO-8		
1	V <sub>OUT</sub>	10 V, ±4.0%, 100 mA output.
2	V <sub>OUT</sub> Sense	Kelvin connection which allows remote sensing of output voltage for improved regulation. If remote sensing is not required, connect to V <sub>OUT</sub> .
3	ENABLE	Logic level switches output off when toggled HIGH.
4	GND	Ground. All GND leads must be connected to Ground.
5	RESET	Active reset (accurate to V <sub>OUT</sub> ≥ 1.0 V).
6, 7	NC	No connection.
8	V <sub>IN</sub>	Input voltage.

## CIRCUIT DESCRIPTION

## VOLTAGE REFERENCE AND OUTPUT CIRCUITRY

## Output Stage Protection

The output stage is protected against overvoltage, short circuit and thermal runaway conditions (Figure 2).

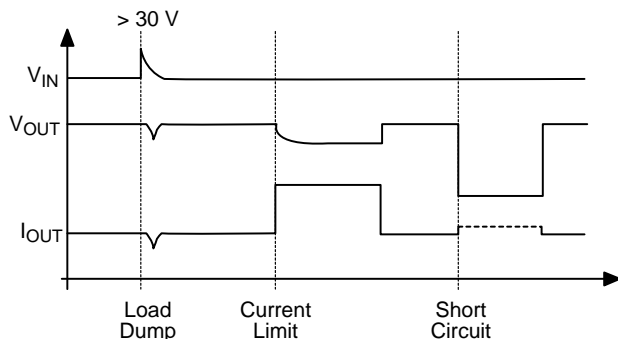


Figure 2. Typical Circuit Waveforms for Output Stage Protection

If the input voltage rises above 30 V (e.g. load dump), the output shuts down. This response protects the internal circuitry and enables the IC to survive unexpected voltage transients.

Should the junction temperature of the power device exceed 180°C (typ) the load current capability is reduced thereby preventing thermal overload. This thermal management function is an effective means to prevent die overheating since the load current is the principle heat source in the IC.

## REGULATOR CONTROL FUNCTIONS

The CS8311 contains two microprocessor compatible control functions:  $\overline{\text{ENABLE}}$  and  $\overline{\text{RESET}}$  (Figure 3).

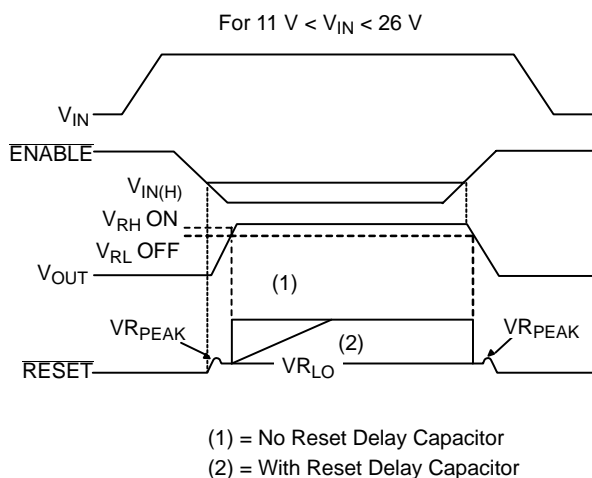


Figure 3. Circuit Waveform

 $\overline{\text{ENABLE}}$  Function

The  $\overline{\text{ENABLE}}$  function switches the output transistor ON and OFF. When the voltage on the  $\overline{\text{ENABLE}}$  lead exceeds 1.4 V typ, the output pass transistor turns off, leaving a high impedance facing the load. The IC will remain in Sleep mode, drawing only 50  $\mu\text{A}$  (max), until the voltage on this input drops below the  $\overline{\text{ENABLE}}$  threshold.

 $\overline{\text{RESET}}$  Function

A  $\overline{\text{RESET}}$  signal (low voltage) is generated as the IC powers up until  $V_{\text{OUT}}$  is within 1.0 V of the regulated output voltage, or when  $V_{\text{OUT}}$  drops out of regulation, and is lower than 1.1 V below the regulated output voltage. A hysteresis of 50 mV is included in the function to minimize oscillations.

The  $\overline{\text{RESET}}$  output is an open collector NPN transistor, controlled by a low voltage detection circuit. The circuit is functionally independent of the rest of the IC thereby guaranteeing that the  $\overline{\text{RESET}}$  signal is valid for  $V_{\text{OUT}}$  as low as 1.0 V.

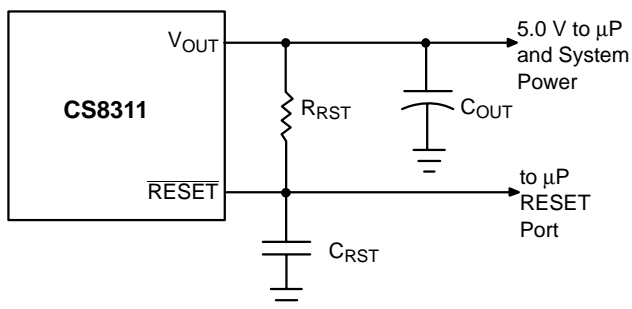


Figure 4. RC Network for  $\overline{\text{RESET}}$  Delay

An external RC network on the lead (Figure 4) provides a sufficiently long delay for most microprocessor based applications. RC values can be chosen using the following formula:

$$R_{\text{TOT}}C_{\text{RST}} = \left[ \frac{-t_{\text{Delay}}}{\ln\left(\frac{V_T - V_{\text{OUT}}}{V_{\text{RST}} - V_{\text{OUT}}}\right)} \right]$$

where:

$R_{\text{RST}}$  =  $\overline{\text{RESET}}$  Delay resistor

$R_{\text{IN}}$  =  $\mu\text{P}$  port impedance

$R_{\text{TOT}}$  =  $R_{\text{RST}}$  in parallel with  $R_{\text{IN}}$

$C_{\text{RST}}$  =  $\overline{\text{RESET}}$  Delay capacitor

$t_{\text{Delay}}$  = desired delay time

$V_{\text{RST}} = V_{\text{SAT}}$  of  $\overline{\text{RESET}}$  lead (0.7 V @ turn – ON)

$V_T$  =  $\overline{\text{RESET}}$  threshold.

## APPLICATION NOTES

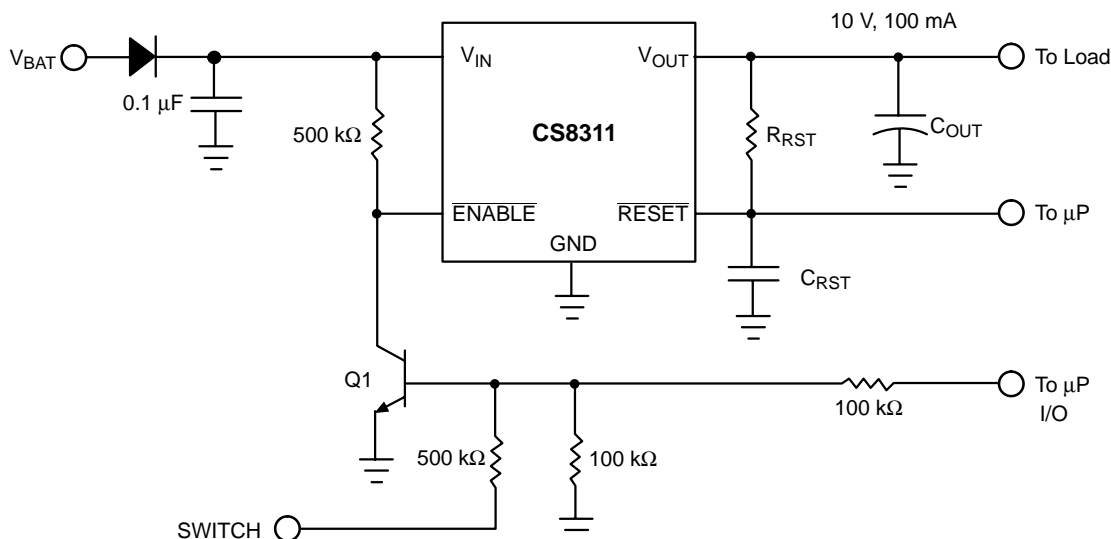


Figure 5. Microprocessor Control of CS8311 Using External Switching Transistor Q1

The circuit depicted in Figure 5 lets the system control its power source, the CS8311 regulator. A SWITCH (potentially an I/O port on microprocessor) is used to drive the base of Q1. When Q1 is driven into saturation, the voltage on the  $\overline{\text{ENABLE}}$  lead falls below its lower threshold. The regulator's output is enabled. When the drive current is removed, the voltage on the  $\overline{\text{ENABLE}}$  lead rises, the output is switched off and the IC moves into Sleep mode where it draws 50  $\mu\text{A}$  (max).

By coupling these two controls with the  $\overline{\text{ENABLE}}$  lead, the system has added flexibility. Once the system is running, the state of the SWITCH is irrelevant as long as the I/O port continues to drive Q1. The microprocessor can turn off its own power by withdrawing drive current, once the SWITCH is open. This software control at the I/O port allows the microprocessor to finish key housekeeping functions before power is removed.

The logic options are summarized in Table 1.

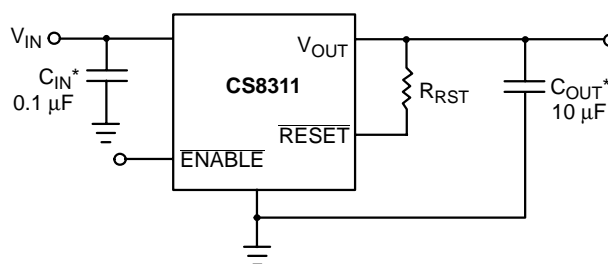
Table 1. Logic Control of CS8311 Output

Microprocessor I/O Drive	Switch	$\overline{\text{ENABLE}}$	Output
ON	Closed	LOW	ON
	Open	LOW	ON
OFF	Closed	LOW	ON
	Open	HIGH	OFF

The I/O port of the microprocessor typically provides 50  $\mu\text{A}$  to Q1. In automotive applications the SWITCH is connected to the ignition switch.

## STABILITY CONSIDERATIONS

The output or compensation capacitor helps determine three main characteristics of a linear regulator: start-up delay, load transient response and loop stability.



\* $C_{IN}$  required if regulator is located far from the power supply filter.

\*\* $C_{OUT}$  required for stability. Capacitor must operate at minimum temperature expected.

Figure 6. Test and Application Circuit Showing Output Compensation

The capacitor value and type should be based on cost, availability, size and temperature constraints. A tantalum or aluminum electrolytic capacitor is best, since a film or ceramic capacitor with almost zero ESR can cause instability. The aluminum electrolytic capacitor is the least expensive solution, but, if the circuit operates at low temperatures ( $-25^{\circ}\text{C}$  to  $-40^{\circ}\text{C}$ ), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturers data sheet usually provides this information.

The value for the output capacitor  $C_{OUT}$  shown in Figure 6 should work for most applications, however it is not necessarily the optimized solution.

To determine an acceptable value for  $C_{OUT}$  for a particular application, start with a tantalum capacitor of the recommended value and work towards a less expensive alternative part.

**Step 1:** Place the completed circuit with a tantalum capacitor of the recommended value in an environmental chamber at the lowest specified operating temperature and monitor the outputs with an oscilloscope. A decade box connected in series with the capacitor will simulate the higher ESR of an aluminum capacitor. Leave the decade box outside the chamber, the small resistance added by the longer leads is negligible.

**Step 2:** With the input voltage at its maximum value, increase the load current slowly from zero to full load while observing the output for any oscillations. If no oscillations are observed, the capacitor is large enough to ensure a stable design under steady state conditions.

**Step 3:** Increase the ESR of the capacitor from zero using the decade box and vary the load current until oscillations appear. Record the values of load current and ESR that cause the greatest oscillation. This represents the worst case load conditions for the regulator at low temperature.

**Step 4:** Maintain the worst case load conditions set in step 3 and vary the input voltage until the oscillations increase. This point represents the worst case input voltage conditions.

**Step 5:** If the capacitor is adequate, repeat steps 3 and 4 with the next smaller valued capacitor. A smaller capacitor will usually cost less and occupy less board space. If the output oscillates within the range of expected operating conditions, repeat steps 3 and 4 with the next larger standard capacitor value.

**Step 6:** Test the load transient response by switching in various loads at several frequencies to simulate its real working environment. Vary the ESR to reduce ringing.

**Step 7:** Raise the temperature to the highest specified operating temperature. Vary the load current as instructed in step 5 to test for any oscillations.

Once the minimum capacitor value with the maximum ESR is found, a safety factor should be added to allow for the tolerance of the capacitor and any variations in regulator performance. Most good quality aluminum electrolytic capacitors have a tolerance of  $\pm 20\%$  so the minimum value found should be increased by at least 50% to allow for this tolerance plus the variation which will occur at low temperatures. The ESR of the capacitor should be less than 50% of the maximum allowable ESR found in step 3 above.

#### CALCULATING POWER DISSIPATION IN A SINGLE OUTPUT LINEAR REGULATOR

The maximum power dissipation for a single output regulator (Figure 7) is:

$$P_{D(max)} = (V_{IN(max)} - V_{OUT(min)})I_{OUT(max)} + V_{IN(max)}I_Q \quad (1)$$

where:

$V_{IN(max)}$  is the maximum input voltage,

$V_{OUT(min)}$  is the minimum output voltage,

$I_{OUT(max)}$  is the maximum output current for the application, and

$I_Q$  is the quiescent current the regulator consumes at  $I_{OUT(max)}$ .

Once the value of  $P_{D(max)}$  is known, the maximum permissible value of  $R_{\theta JA}$  can be calculated:

$$R_{\theta JA} = \frac{150^{\circ}\text{C} - T_A}{P_D} \quad (2)$$

The value of  $R_{\theta JA}$  can then be compared with those in the package section of the data sheet. Those packages with  $R_{\theta JA}$ 's less than the calculated value in equation 2 will keep the die temperature below  $150^{\circ}\text{C}$ .

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heatsink will be required.

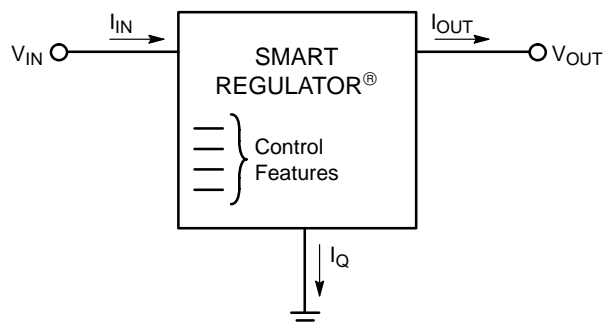


Figure 7. Single Output Regulator With Key Performance Parameters Labeled

#### HEAT SINKS

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of  $R_{\theta JA}$ .

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CS} + R_{\theta SA} \quad (3)$$

where:

$R_{\theta JC}$  = the junction-to-case thermal resistance,

$R_{\theta CS}$  = the case-to-heatsink thermal resistance, and

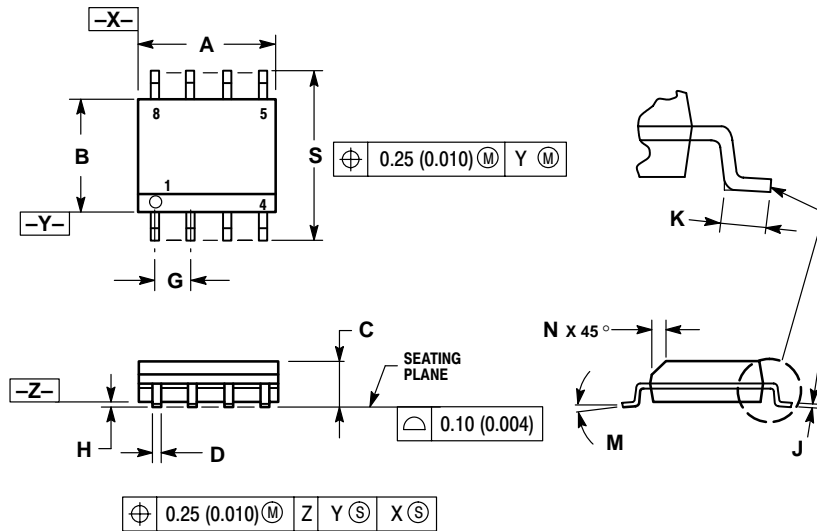
$R_{\theta SA}$  = the heatsink-to-ambient thermal resistance.

$R_{\theta JC}$  appears in the package section of the data sheet. Like  $R_{\theta JA}$ , it too is a function of package type.  $R_{\theta CS}$  and  $R_{\theta SA}$  are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heat sink manufacturers.

# CS8311

## PACKAGE DIMENSIONS

SO-8  
D SUFFIX  
CASE 751-07  
ISSUE W



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

### PACKAGE THERMAL DATA

Parameter		SO-8	Unit
R <sub>θJC</sub>	Typical	45	°C/W
R <sub>θJA</sub>	Typical	165	°C/W

SMART REGULATOR is a registered trademark of Semiconductor Components Industries, LLC (SCILLC).

**ON Semiconductor** and  are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

## PUBLICATION ORDERING INFORMATION

### NORTH AMERICA Literature Fulfillment:

Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** ONlit@hibbertco.com  
Fax Response Line: 303-675-2167 or 800-344-3810 Toll Free USA/Canada

**N. American Technical Support:** 800-282-9855 Toll Free USA/Canada

**EUROPE:** LDC for ON Semiconductor – European Support

**German Phone:** (+1) 303-308-7140 (Mon-Fri 2:30pm to 7:00pm CET)  
**Email:** ONlit-german@hibbertco.com

**French Phone:** (+1) 303-308-7141 (Mon-Fri 2:00pm to 7:00pm CET)  
**Email:** ONlit-french@hibbertco.com

**English Phone:** (+1) 303-308-7142 (Mon-Fri 12:00pm to 5:00pm GMT)  
**Email:** ONlit@hibbertco.com

**EUROPEAN TOLL-FREE ACCESS\*: 00-800-4422-3781**

\*Available from Germany, France, Italy, UK, Ireland

### CENTRAL/SOUTH AMERICA:

**Spanish Phone:** 303-308-7143 (Mon-Fri 8:00am to 5:00pm MST)  
**Email:** ONlit-spanish@hibbertco.com

**Toll-Free from Mexico:** Dial 01-800-288-2872 for Access –  
then Dial 866-297-9322

**ASIA/PACIFIC:** LDC for ON Semiconductor – Asia Support

**Phone:** 1-303-675-2121 (Tue-Fri 9:00am to 1:00pm, Hong Kong Time)  
**Toll Free from Hong Kong & Singapore:**

**001-800-4422-3781**

**Email:** ONlit-asia@hibbertco.com

**JAPAN:** ON Semiconductor, Japan Customer Focus Center

4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-0031

**Phone:** 81-3-5740-2700

**Email:** r14525@onsemi.com

**ON Semiconductor Website:** <http://onsemi.com>

For additional information, please contact your local Sales Representative.